

<b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b> ( Not for submission under 37 CFR 1.99)	Application Number		09928737
	Filing Date		2001-08-13
	First Named Inventor	QUAN, SON KY	
	Art Unit	2831	
	Examiner Name	NGO, HUNG V.	
	Attorney Docket Number	SC09785T-CD1	

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	2	05-67705	JP		1993-03-19	KAZUHIKO et al.	English Abstract attached	<input type="checkbox"/>
	3	07-193162	JP		1995-07-28	AKIRO et al.	English Abstract attached	<input type="checkbox"/>
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11	05129517	JP		1993-05-25	SUP	English Abstract attached	<input type="checkbox"/>
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14	06169051	JP		1994-06-14	NAOTO et al	English Abstract attached	<input type="checkbox"/>
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